



**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Re the Application of: **Miwa KOZAWA et al.**

Group Art Unit: **1752**

Application Number: **10/629,806**

Examiner: **Sin J. Lee**

Filed: **July 30, 2003**

Confirmation Number: **9494**

For: **RESIST PATTERN THICKENING MATERIAL, PROCESS FOR  
FORMING RESIST PATTERN, AND PROCESS FOR  
MANUFACTURING SEMICONDUCTOR DEVICE**

Attorney Docket Number: **030923**

Customer Number: **38834**

**AMENDMENT**

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

July 20, 2006

Sir:

This paper is filed in response to the Office Action dated April 24, 2006.

**Amendments to the Claims** begin on page 2 of this paper.

**Remarks** begin on page 8 of this paper.